3.0mmx1.5mm SMD CHIP LED LAMP

Part Number: APL3015SYCK-F01

Super Bright Yellow

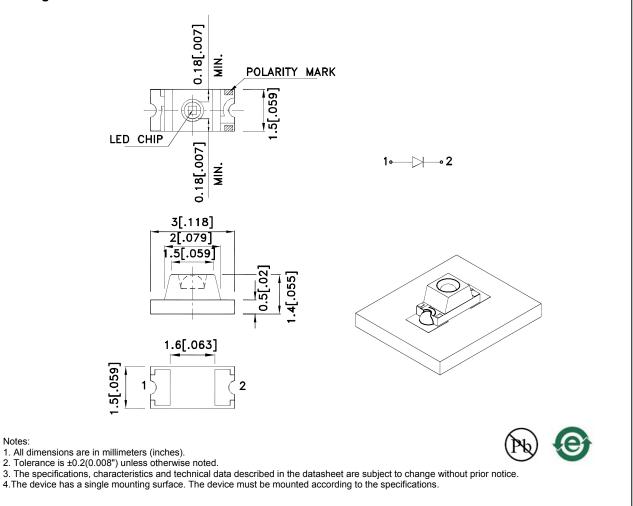
Features

- 3.0mmx1.5mm SMT LED, 1.4mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Super Bright Yellow device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Package Dimensions



SPEC NO: DSAF1079 APPROVED: WYNEC REV NO: V.4 CHECKED: Allen Liu DATE: APR/19/2011 DRAWN: J.Yu PAGE: 1 OF 5 ERP: 1203001632

Selection Guide

Selection Guide					
Part No. Dice		Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APL3015SYCK-F01	Super Bright Yellow (AlGaInP)	Water Clear	180	350	70°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Yellow	590		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	20		nm	I⊧=20mA
С	Capacitance	Super Bright Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Yellow	2	2.5	V	IF=20mA
lr	Reverse Current	Super Bright Yellow		10	uA	Vr=5V

Notes:

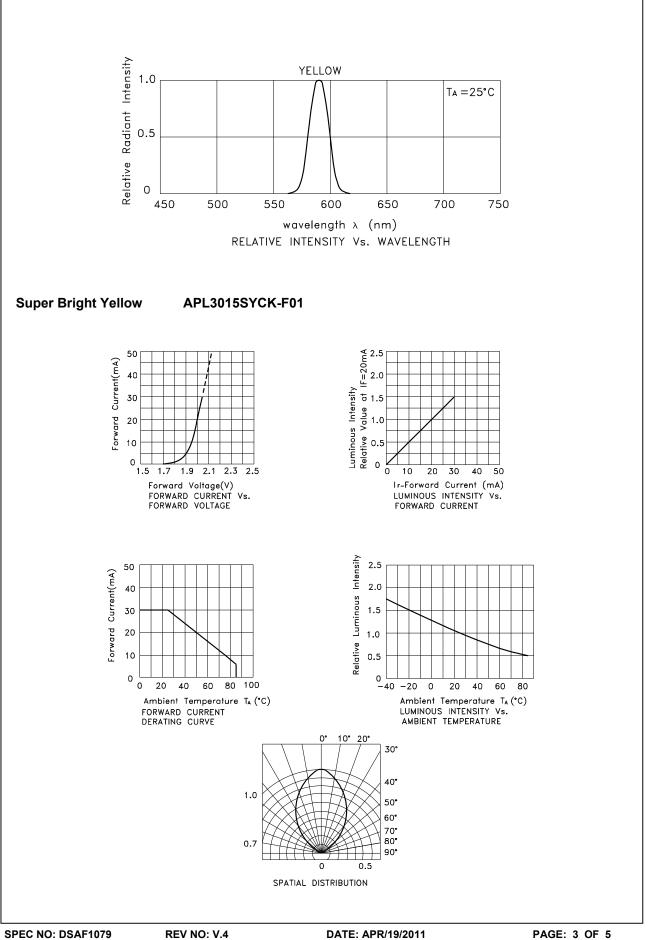
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Yellow	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	175	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:

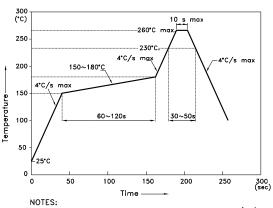
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



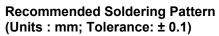
APL3015SYCK-F01

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

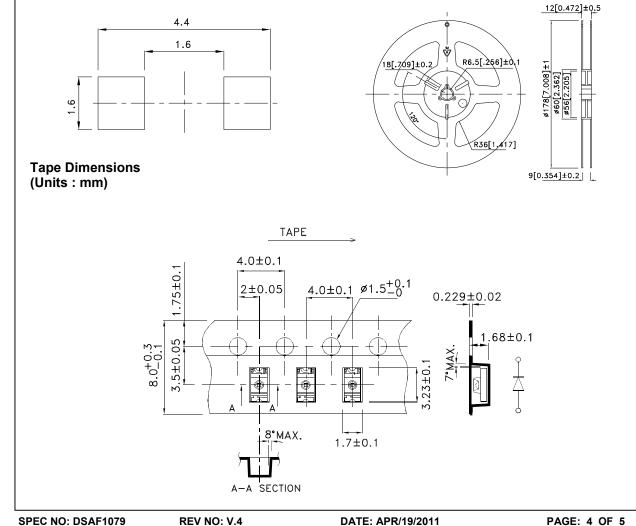
Reflow Soldering Profile For Lead-free SMT Process.



NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.



Reel Dimension



CHECKED: Allen Liu

DRAWN: J.Yu

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